

**PRODUCT FLOW SUMMARY  
TYPICAL DEI CERAMIC PACKAGES**

<b>PROCESS DESCRIPTION</b>	<b>883/B</b>	<b>STD</b>	<b>STD BURN-IN</b>	<b>NOTES</b>
<b>INCOMING WAFER INSPECTION</b>	YES	YES	YES	
<b>WAFER PROBE</b>	100%	SAMPLE	SAMPLE	
<b>WAFER SAW</b>	YES	YES	YES	
<b>2<sup>ND</sup> OPTICAL INSPECTION</b>	100%	100%	100%	883 M2010 Cond B
<b>DIE ATTACH</b>	YES	YES	YES	Monitor 883 M2027
<b>WIRE BOND</b>	YES	YES	YES	Monitor 883 M2011 Cond D
<b>3<sup>RD</sup> OPTICAL INSPECTION</b>	100%	100%	100%	883 M2010 Cond B
<b>LID CAP &amp; SEAL</b>	YES	YES	YES	
<b>TEMP CYCLE</b>	100%	100%	100%	883 M1010.7 Cond C, 10 Cy
<b>CENTRIFUGE</b>	100%	NO	NO	883 M2001 Cond E, Y1 axis
<b>MARK</b>	YES	YES	YES	Monitor 883 M2015
<b>GROSS &amp; FINE LEAK</b>	100%	100%	100%	882 M1014.10 Cond C1 & A1
<b>VISUAL INSPECTION</b>	100%	100%	100%	883 M2009
<b>PRE-BURN IN ELECTRICAL TEST, ROOM</b>	100%	NO	100%	
<b>ELECTRICAL TEST, HOT &amp; COLD</b>	SAMPLE or 100%	NO	SAMPLE or 100%	As required by product
<b>BURN-IN</b>	100%	NO	100%	883 M1015 Class B
<b>ELECTRICAL TEST @ ROOM</b>	100%	100%	100%	5% PDA
<b>ELECTRICAL TEST HOT</b>	100%	100%	100%	
<b>ELECTRICAL TEST COLD</b>	100%	0.65% AQL	0.65% AQL	

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<b>GROSS &amp; FINE LEAK</b>	100%	NO	NO	882 M1014.10 Cond C1 & A1
<b>FINAL VISUAL INSPECTION</b>	100%	100%	100%	883 M2009
<b>PACK &amp; SHIP</b>	YES	YES	YES	
<b>QCI GROUP A INSPECTIONS</b>	Each lot	NO	NO	883 M5005
<b>QCI GROUP B INSPECTIONS</b>	Each lot	NO	NO	883 M5005
<b>QCI GROUP C INSPECTIONS</b>	Periodic	NO	NO	883 M5005
<b>QCI GROUP D INSPECTIONS</b>	Periodic	NO	NO	883 M5005